

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type

# SSM3J36FS

## ○ Power Management Switches

- 1.5-V drive
- Low ON-resistance:  $R_{ON} = 3.60 \Omega$  (max) (@ $V_{GS} = -1.5 V$ )  
 :  $R_{ON} = 2.70 \Omega$  (max) (@ $V_{GS} = -1.8 V$ )  
 :  $R_{ON} = 1.60 \Omega$  (max) (@ $V_{GS} = -2.8 V$ )  
 :  $R_{ON} = 1.31 \Omega$  (max) (@ $V_{GS} = -4.5 V$ )

## Absolute Maximum Ratings (Ta = 25 °C)

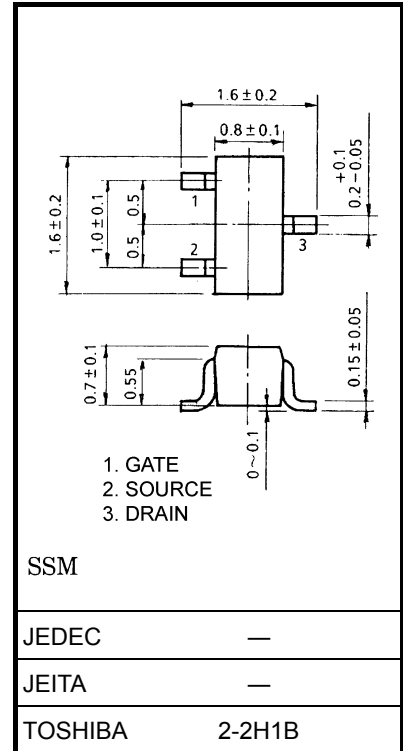
Characteristics	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	-20	V
Gate-source voltage	$V_{GSS}$	$\pm 8$	V
Drain current	DC	$I_D$	-330
	Pulse	$I_{DP}$	-660
Drain power dissipation	$P_D$ (Note1)	150	mW
Channel temperature	$T_{ch}$	150	°C
Storage temperature range	$T_{stg}$	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

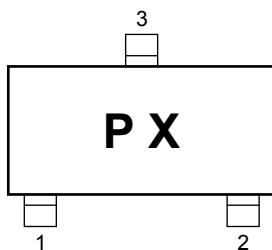
Note1: Mounted on an FR4 board  
 (25.4 mm × 25.4 mm × 1.6mm, Cu Pad: 0.36 mm<sup>2</sup> × 3)

Unit: mm

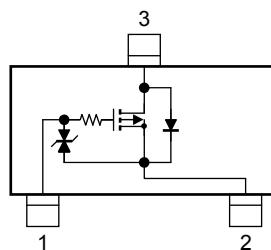


Weight: 2.4 mg (typ.)

## Marking



## Equivalent Circuit (top view)



## Handling Precaution

When handling individual devices (which are not yet mounted on a circuit board), ensure that the environment is protected against static electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

## Usage Considerations

Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to be below  $-1$  mA for the SSM3J36FS). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

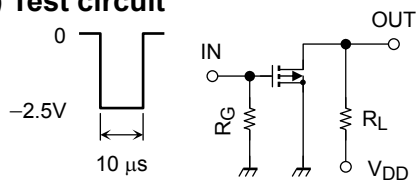
## Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Conditions	Min	Typ.	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	—	—	V
	$V_{(BR)DSX}$	$I_D = -1 \text{ mA}, V_{GS} = 8 \text{ V}$	-12	—	—	
Drain cutoff current	$I_{DSS}$	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	-10	$\mu\text{A}$
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	$\pm 1$	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = -3 \text{ V}, I_D = -1 \text{ mA}$	-0.3	—	-1.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -3 \text{ V}, I_D = -100 \text{ mA}$ (Note2)	190	—	—	mS
Drain-source ON-resistance	$R_{DS(ON)}$	$I_D = -100 \text{ mA}, V_{GS} = -4.5 \text{ V}$ (Note2)	—	0.95	1.31	$\Omega$
		$I_D = -80 \text{ mA}, V_{GS} = -2.8 \text{ V}$ (Note2)	—	1.22	1.60	
		$I_D = -40 \text{ mA}, V_{GS} = -1.8 \text{ V}$ (Note2)	—	1.80	2.70	
		$I_D = -30 \text{ mA}, V_{GS} = -1.5 \text{ V}$ (Note2)	—	2.23	3.60	
Input capacitance	$C_{iss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	43	—	pF
Output capacitance	$C_{oss}$					
Reverse transfer capacitance	$C_{rss}$					
Total Gate Charge	$Q_g$	$V_{DS} = -10 \text{ V}, I_{DS} = -330 \text{ mA}$ $V_{GS} = -4 \text{ V}$	—	1.2	—	nC
Gate-Source Charge	$Q_{gs}$					
Gate-Drain Charge	$Q_{gd}$					
Switching time	Turn-on time	$t_{on}$	$V_{DD} = -10 \text{ V}, I_D = -100 \text{ mA}$ $V_{GS} = 0 \text{ to } -2.5 \text{ V}, R_G = 50 \Omega$	—	90	ns
	Turn-off time	$t_{off}$		—	200	
Drain-source forward voltage	$V_{DSF}$	$I_D = 330 \text{ mA}, V_{GS} = 0 \text{ V}$ (Note2)	—	0.88	1.2	V

Note2: Pulse test

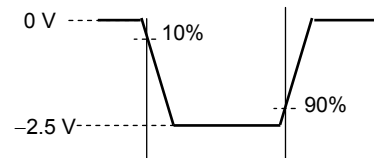
## Switching Time Test Circuit

(a) Test circuit

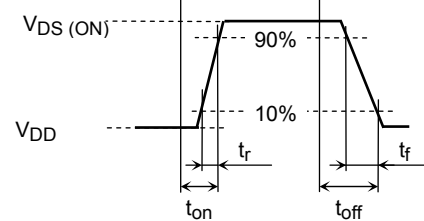


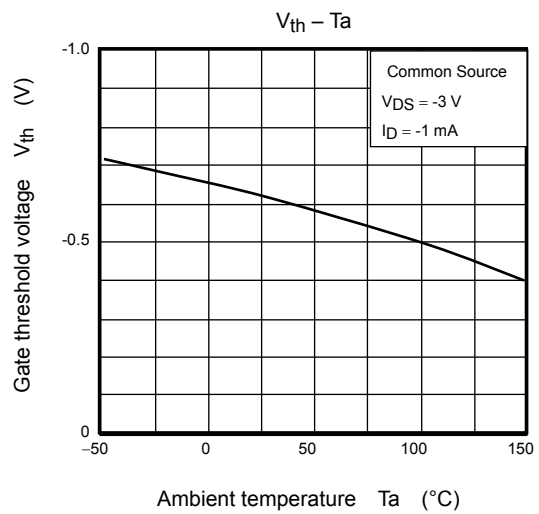
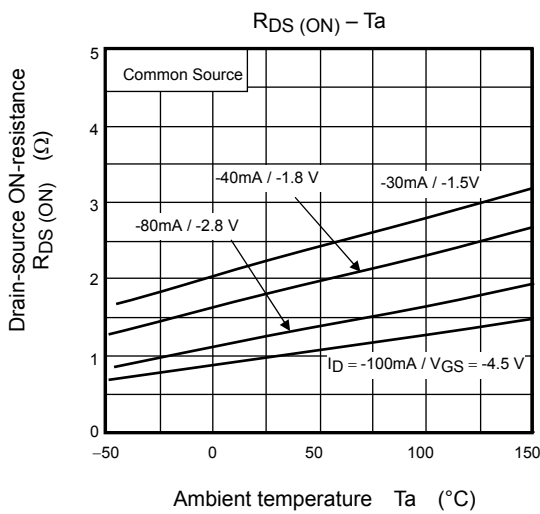
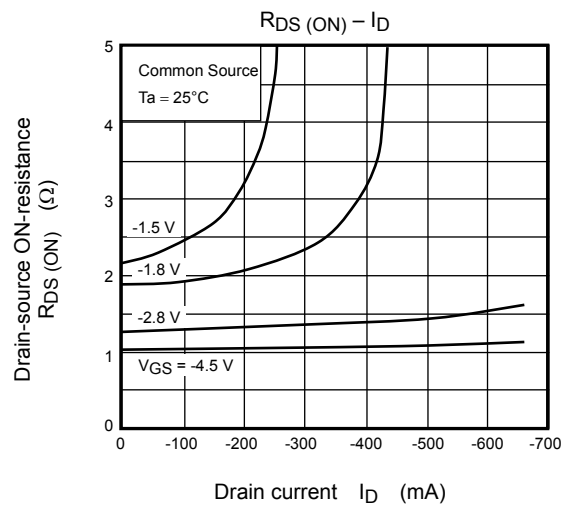
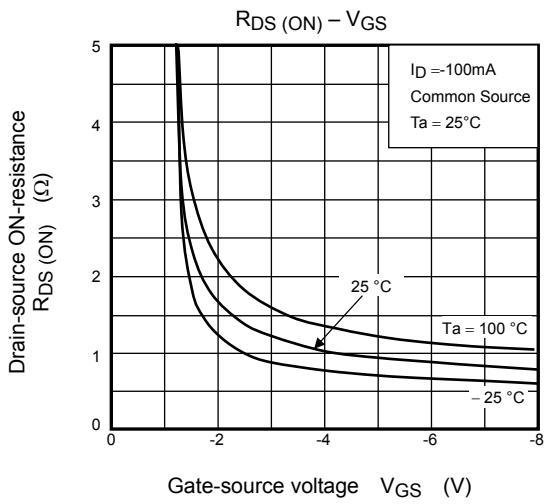
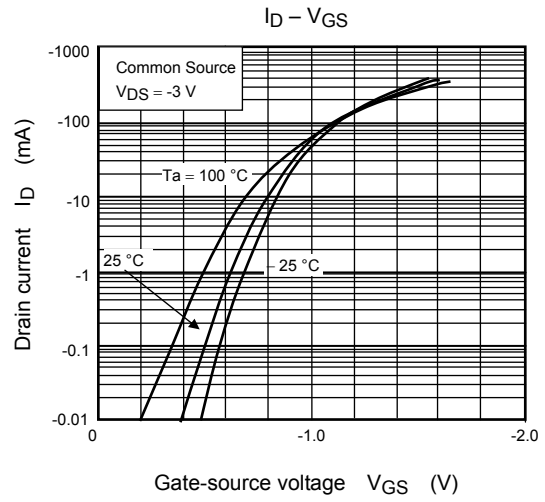
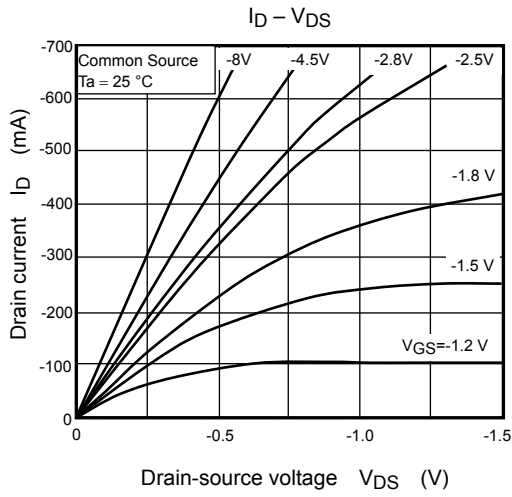
$V_{DD} = -10 \text{ V}$   
 Duty  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5 \text{ ns}$   
 ( $Z_{out} = 50 \Omega$ )  
 Common Source  
 $T_a = 25^\circ\text{C}$

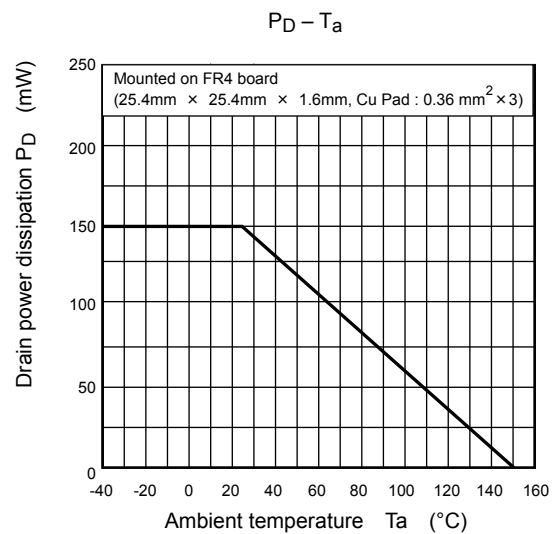
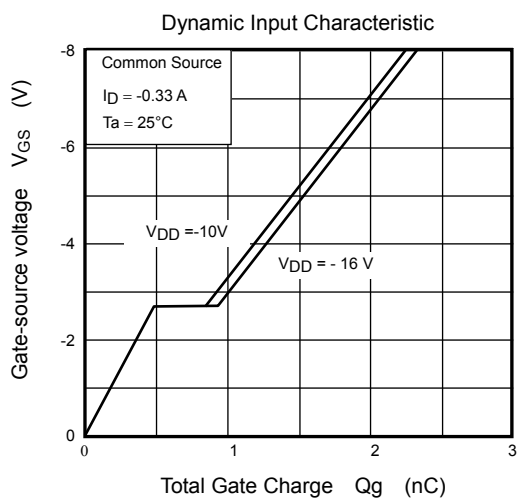
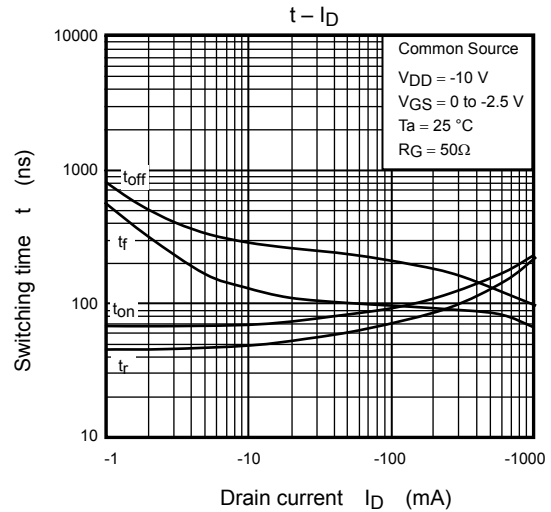
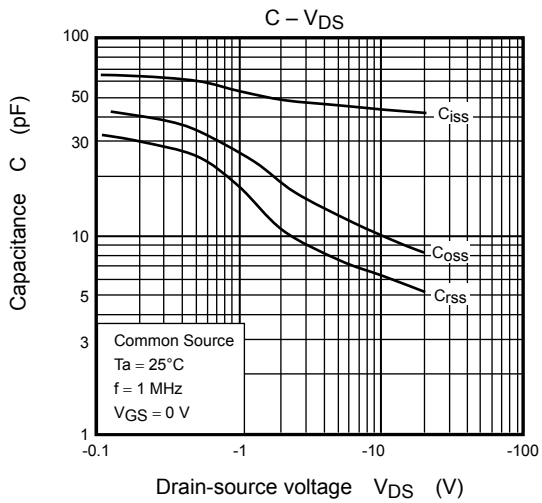
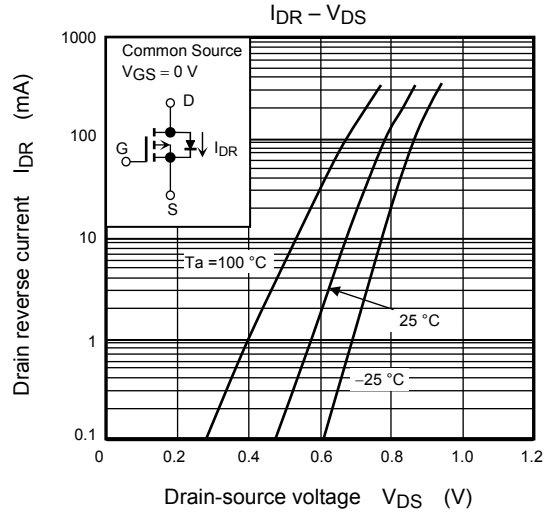
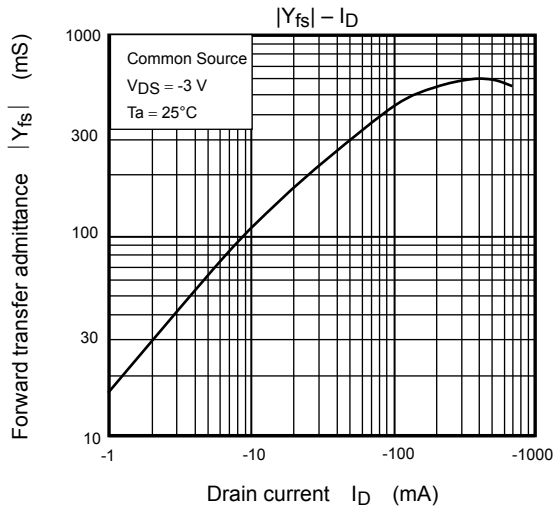
(b)  $V_{IN}$



(c)  $V_{OUT}$







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